



General Description

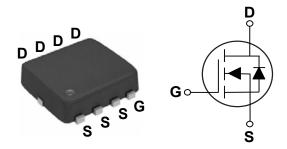
These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BV _{DSS}	R _{DS(ON)}	I _D
100 V	18 mΩ	42 A

Features

- $R_{DS(ON)} \le 18m\Omega@V_{GS} = \overline{10V}$
- · Improved dv/dt Capability
- · Fast Switching
- · Green Device Available

PPAK3X3 Pin Configuration



Applications

- · Synchronous Rectification
- · DC/DC Converter
- Power Management Switches

Absolute Maximum Ratings T_A=25°C unless otherwise noted **Symbol Parameter** Units Rating $V_{\text{DS}} \\$ Drain-Source Voltage 100 ٧ V_{GS} Gate-Source Voltage ±20 V 42 I_{D} Drain Current - Continuous (T_C=25°C) Α Drain Current - Pulsed (NOTE 1) 168 I_{DM} Α **EAS** Single Pulse Avalanche Energy (NOTE 2) 57.8 mJ P_D Power Dissipation (T_C=25°C) 63.45 W T_{J} -55 to 150 Operating Junction Temperature Range ٥С Storage Temperature Range -55 to 150 $\mathsf{T}_{\mathsf{STG}}$ °C Marking Code NM018A

Thermal Characteristics					
Symbol	Parameter	Rating	Unit		
$R_{\theta JA}$	Thermal Resistance Junction to Ambient	48	°C/W		
$R_{ heta JC}$	Thermal Resistance Junction to Case	1.97	°C/W		





Electrical Characteristics (T_{.J}=25°C, unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V_{GS} =0V , I_D =250uA	100			V
I _{DSS}	Drain-Source Leakage Current	V _{DS} =100V , V _{GS} =0V			1	uA
I _{GSS}	Gate-Source Leakage Current	V_{GS} =±20V , V_{DS} =0V			±100	nA

On Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
R _{DS(ON)}	Static Drain-Source On-Resistance	V_{GS} =10V , I_D =12A			18	· mΩ
		V _{GS} =4.5V , I _D =10A			24	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D=250uA$	1		2.5	V
gfs	Forward Transconductance	V _{DS} =10V , I _{DS} =12A		38		S

Dynamic and switching Characteristics (NOTE 4)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Q_g	Total Gate Charge	V _{DS} =50V , V _{GS} =10V , I _D =12A		14		
Q_gs	Gate-Source Charge			2.3		nC
Q_{gd}	Gate-Drain Charge			2.3		
$T_{d(on)}$	Turn-On Delay Time	V_{DD} =50V , V_{GS} =10V , R_{G} =3 Ω , I_{D} =12A		37		
T _r	Rise Time			9.3		nS
$T_{d(off)}$	Turn-Off Delay Time			50		110
T_f	Fall Time			13.6		
C _{iss}	Input Capacitance	V _{DS} =50V , V _{GS} =0V , F=1MHz		910		
C _{oss}	Output Capacitance			400		pF
C _{rss}	Reverse Transfer Capacitance			12		
R_g	Gate Resistance	V_{GS} =0V , V_{DS} =0V , F=1MHz		1.3		Ω

Drain-Source Diode Characteristics and Ratings

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
I _S	Continuous Source Current	V _G =V _D =0V, Force Current			42	Α
V_{SD}	Diode Forward Voltage	V _{GS} =0V , I _S =1A			1.2	V
t _{rr}	Reverse Recovery Time	I _F =12A , di/dt=500A/us		37.9		nS
Q_{rr}	Reverse Recovery Charge			40		nC

NOTES:

- 1. Repetitive Rating: Pulsed width limited by maximum junction temperature.
- 2. The EAS data shows Max. rating. The test condition is V_{DD} =25V, V_{GS} =10V, L=0.4mH, I_{AS} =17A.
- 3. The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%.
- 4. This value is guaranteed by design hence it is not included in the production test.





Characteristics Curves

FIG. 1-Transfer Characteristics

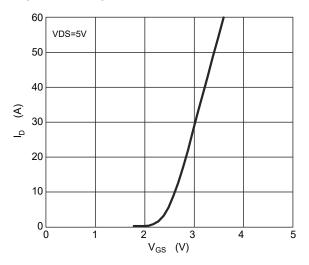


FIG. 2-I $_{\text{S}}$ vs V_{SD}

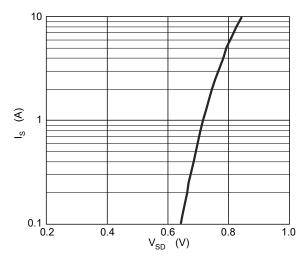


FIG. 3-R $_{\rm DS(on)}$ vs $\rm I_{\rm D}$

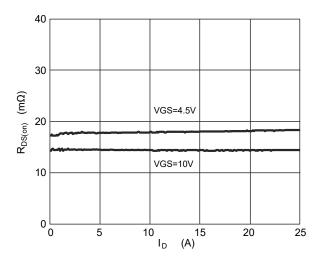


FIG. 4-Normalized R_{DS(ON)} vs T_J

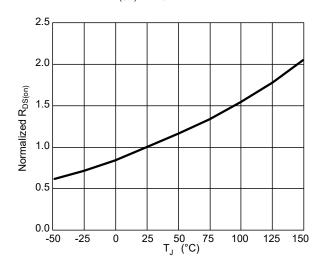


FIG. 5-Gate Charge Characteristics

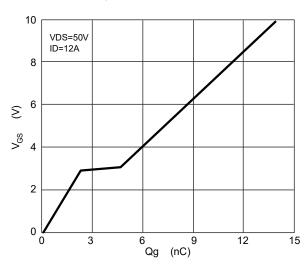
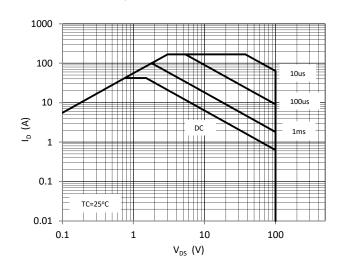


FIG. 6-Safe Operating Area

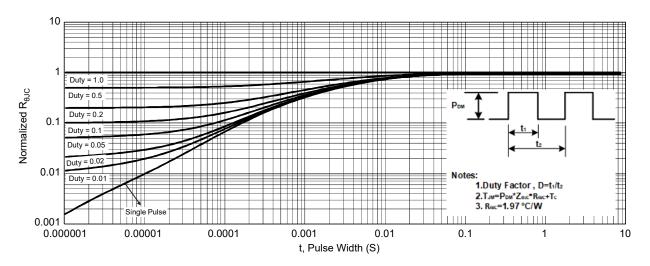




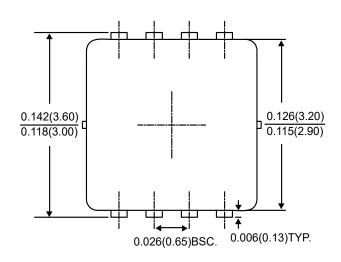


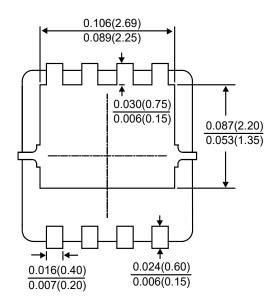
Characteristics Curves

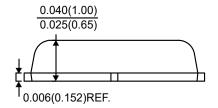
FIG. 7-Transient Thermal Impedance

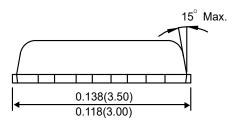


Package Outline Dimensions









PPAK3X3

Dimensions in inches and (millimeters)





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